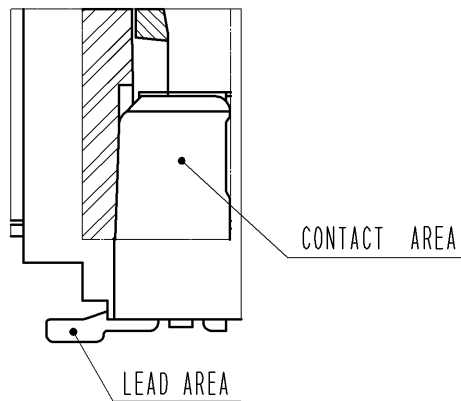
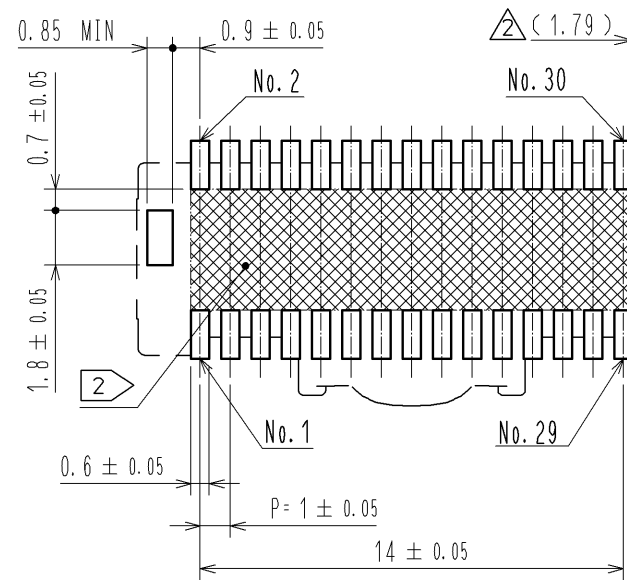


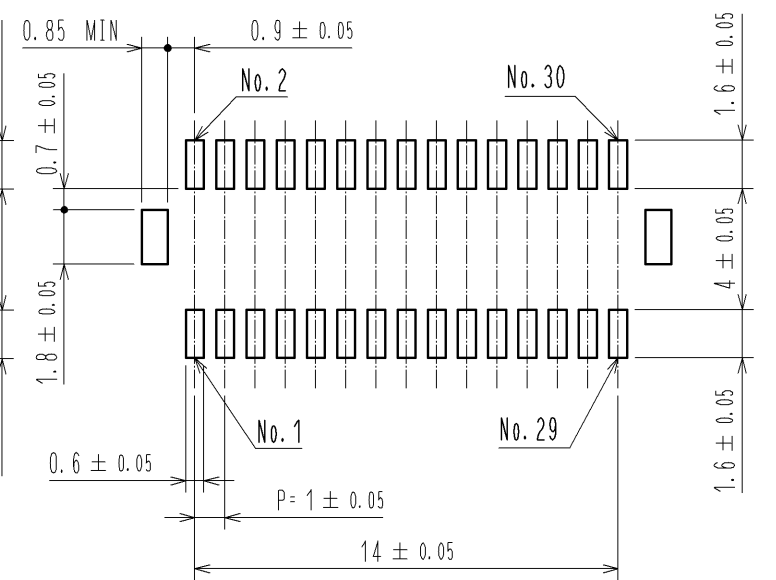
A (10:1)



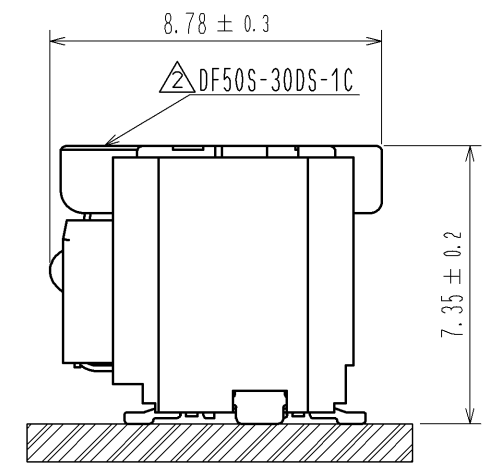
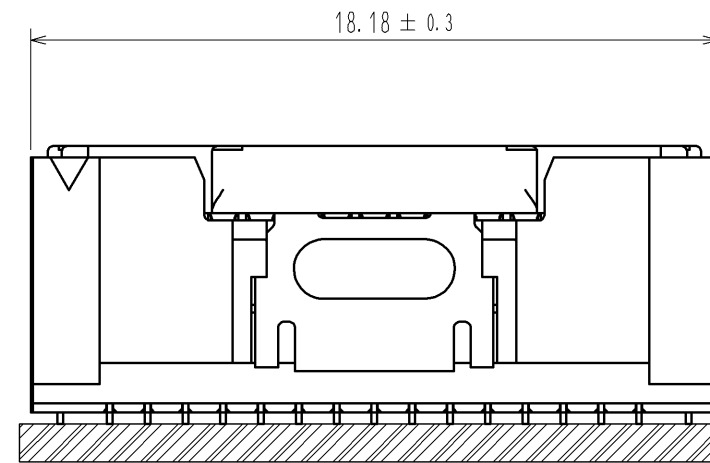
RECOMMENDED PCB LAYOUT (MOUNTING SURFACE SIDE) (FREE)



RECOMMENDED METAL MASK (FREE) THICKNESS : 0.1mm



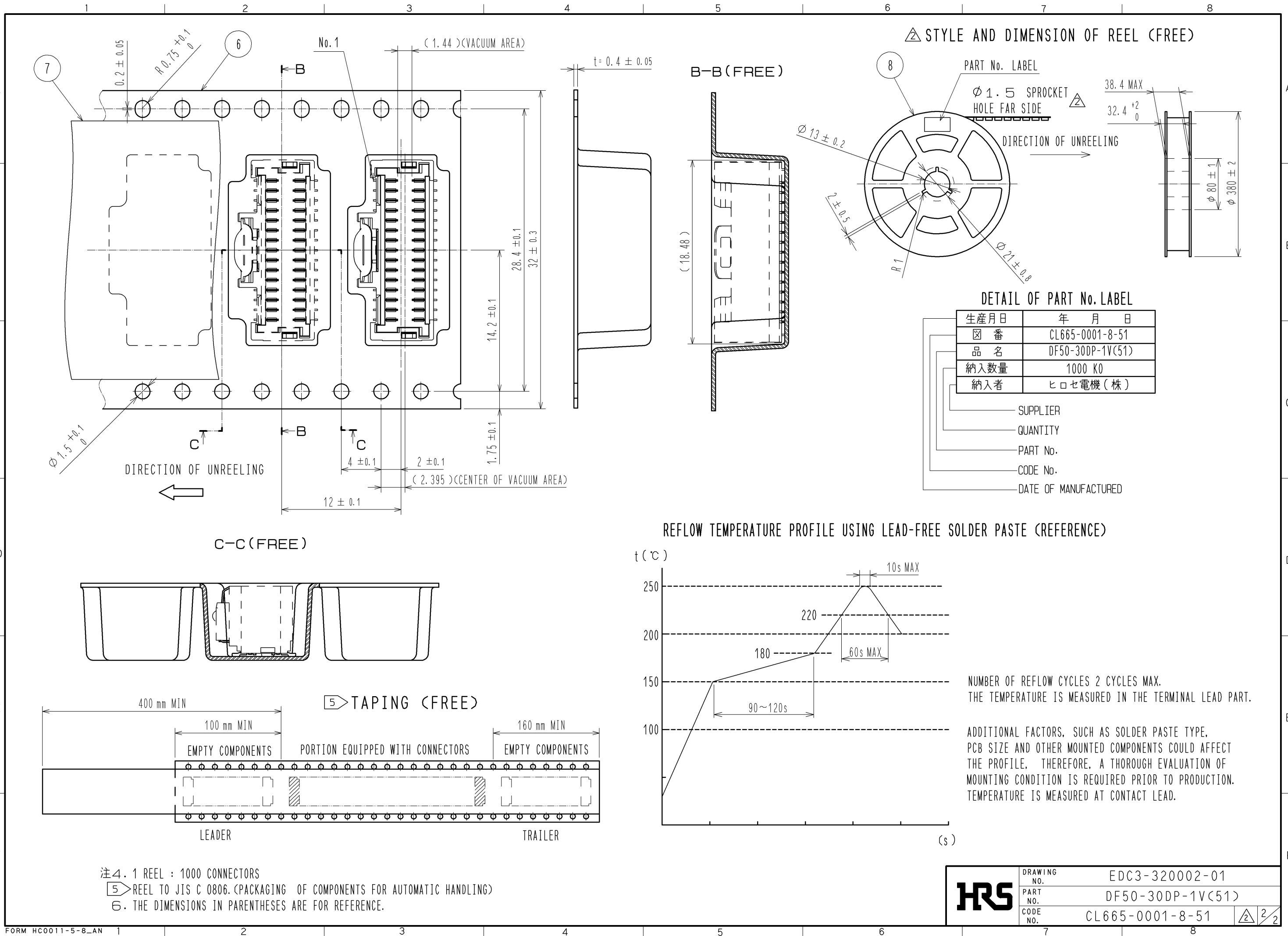
MATING FIGURE (5:1)



- NOTES 1. LEAD CO-PLANARITY SHALL BE 0.1mm MAX
 2. [Hatched Area] AREA INDICATED MUST BE FREE OF CONDUCTIVE TRACES OR THE CONDUCTIVE TRACES MUST BE COVERED BY RESIST FILM.
 3. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MOUNTED TO FPC.

3	BRASS	CONTACT AREA : Au PLATING 0.05μm MIN LEAD AREA : Au PLATING 0.05μm MIN UNDER PLATING : Ni PLATING 1μm MIN	8	PS	REEL , BLACK
2	BRASS	CONTACT AREA : Au PLATING 0.05μm MIN LEAD AREA : Au PLATING 0.05μm MIN UNDER PLATING : Ni PLATING 1μm MIN	7	POLYESTER	CLEAR
1	LCP	BLACK , UL94V-0	6	PS	CLEAR
			5	STAINLESS STEEL	—
			4	BRASS	CONTACT AREA : Sn PLATING 1μm MIN UNDER PLATING : Ni PLATING 0.5μm MIN
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS

UNITS mm		SCALE FREE	COUNT 5	DESCRIPTION OF REVISIONS DIS-H-007735	DESIGNED MI. SAKIMURA	CHECKED TS. KUMAZAWA	DATE 13. 03. 22
HRS HIROSE ELECTRIC CO., LTD.		APPROVED : TS. SAKATA	09. 12. 04	DRAWING NO. EDC3-320002-01			
		CHECED : MN. KENJO	09. 12. 04	PART NO. DF50-30DP-1V(51)			
		DESIGNED : TT. OHSAKO	09. 12. 04	CODE NO. CL665-0001-8-51			
		DRAWN : TT. OHSAKO	09. 12. 04				



HRS	DRAWING NO.	EDC3-320002-01
	PART NO.	DF50-30DP-1V(51)
	CODE NO.	CL665-0001-8-51
		2/2